

**I. AMENDMENTS TO THE CLAIMS:**

Please cancel claims 2, 21 and 22 without prejudice. Kindly amend claims 1, 11, 13, 16 and 20, and add new claims 23-26 as follows.

The following Listing of Claims replaces all prior Listings, or versions, of claims in the above-captioned application.

**LISTING OF CLAIMS:**

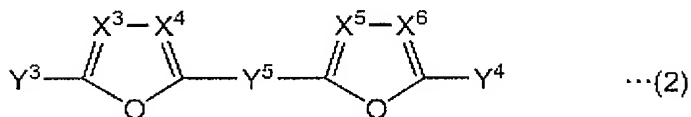
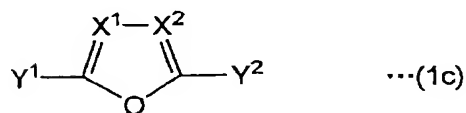
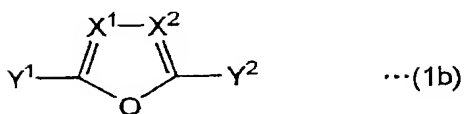
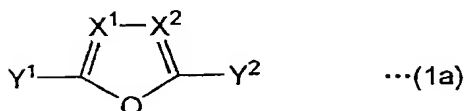
1. (Currently Amended) A photosensitive resin composition comprising:

(A) a binder polymer;

(B) a photopolymerizing compound with an ethylenic unsaturated bond;

(C) a photopolymerization initiator; and

(D) a compound represented by the following general formula (1a), (1b), (1c), or (2),

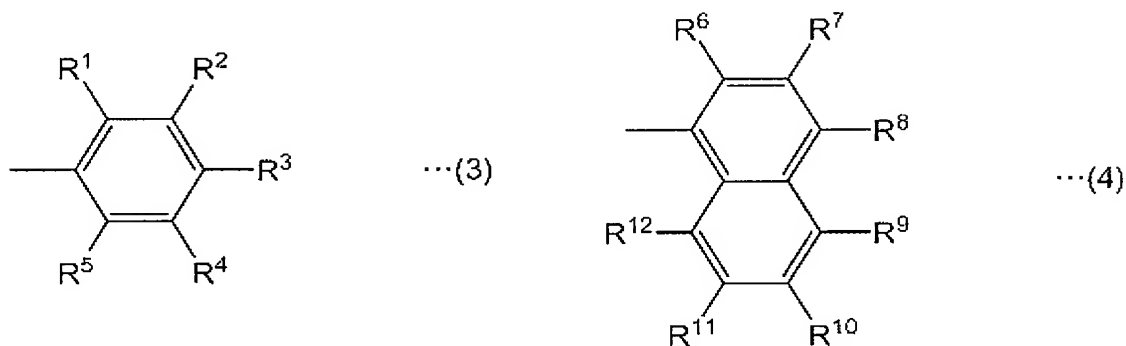


wherein

in formula (1a),  $X^1$  represents a CH group, a  $CCH_3$  group, a  $CC_2H_5$  group, or nitrogen,  $X^2$  represents a CH group, a  $CCH_3$  group, or a  $CC_2H_5$  group, and  $Y^1$  and  $Y^2$  represent mutually different optionally substituted aryl;

in formula (1b),  $X^1$  and  $X^2$  both represent nitrogen, and  $Y^1$  and  $Y^2$  represent mutually different optionally substituted aryl;

in formula (1c),  $X^1$  and  $X^2$  both represent nitrogen and  $Y^1$  and  $Y^2$  both represent mutually the same group represented by formula (3) or formula (4)



wherein in formulae (3) and (4), at least one of  $R^1$ ,  $R^2$ ,  $R^3$ ,  $R^4$ ,  $R^5$ ,  $R^6$ ,  $R^7$ ,  $R^8$ ,  $R^9$ ,  $R^{10}$ ,  $R^{11}$ ,  $R^{12}$  represents C1-20 alkyl and the other represent hydrogen; and

in formula (2),  $X^3$ ,  $X^4$ ,  $X^5$  and  $X^6$  each independently represent a CH group, a  $CCH_3$  group, a  $CC_2H_5$  group or nitrogen,  $Y^3$  and  $Y^4$  each independently represent optionally substituted aryl, and  $Y^5$  represents optionally substituted arylene,

wherein the acid value of component (A) is 45-200 mg KOH/g, and

wherein component (A) contains polymerizable monomer with a carboxyl group, (meth)acrylic acid alkyl esters, and styrene or a styrene derivative as a copolymerizing

component, component (B) contains a bisphenol A-type (meth)acrylate compound, and  
component (C) contains a 2,4,5-triarylimidazole dimer.

2. (Cancelled)

3. (Cancelled)

4. (Previously Presented) A photosensitive resin composition according to claim 1,  
wherein the weight-average molecular weight of component (A) is 20,000-300,000.

5. (Previously Presented) A photosensitive resin composition according to claim 1,  
wherein the component (A) content is 20-90 parts by weight, the component (B) content is  
10-80 parts by weight, the component (C) content is 0.01-20 parts by weight and the  
component (D) content is 0.001-20 parts by weight, with respect to 100 parts by weight as the  
total of component (A) and component (B).

6. (Previously Presented) A photosensitive element comprising a support and a  
photosensitive resin composition layer composed of a photosensitive resin composition  
according to claim 1 formed on the support.

7. (Previously Presented) A resist pattern forming method comprising the steps of:  
laminating a photosensitive resin composition layer for a photosensitive element  
according to claim 6 on a circuit forming board;  
irradiating prescribed sections of the photosensitive resin composition layer with  
active light rays for photocuring of exposed sections; and then

removing non-exposed sections.

8. (Previously Presented) A process for manufacturing a printed circuit board comprising the steps of etching or plating a circuit forming board having a resist pattern formed thereon by a resist pattern forming method according to claim 7.

9. (Cancelled)

10. (Cancelled)

11. (Currently Amended) A photosensitive resin composition according to claim 20~~claim 2~~, wherein the weight-average molecular weight of component (A) is 20,000-300,000.

12. (Cancelled)

13. (Currently Amended) A photosensitive resin composition according to claim 20~~claim 2~~, wherein the component (A) content is 20-90 parts by weight, the component (B) content is 10-80 parts by weight, the component (C) content is 0.01-20 parts by weight and the component (D) content is 0.001-20 parts by weight, with respect to 100 parts by weight as the total of component (A) and component (B).

14. (Cancelled)

15. (Previously Presented) A photosensitive resin composition according to claim 4, wherein the component (A) content is 20-90 parts by weight, the component (B) content is 10-80 parts by weight, the component (C) content is 0.01-20 parts by weight and the component (D) content is 0.001-20 parts by weight, with respect to 100 parts by weight as the total of component (A) and component (B).

16. (Currently Amended) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 20~~claim 2~~ formed on the support.

17. (Cancelled)

18. (Previously Presented) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 4 formed on the support.

19. (Previously Presented) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 5 formed on the support.

20. (Currently Amended) A photosensitive resin composition comprising:  
(A) a binder polymer;  
(B) a photopolymerizing compound with an ethylenic unsaturated bond;  
(C) a photopolymerization initiator; and  
(D) one or more compounds selected from the group consisting of 2,5-diphenylfuran,

2,5-diphenyl-3,4-dimethylfuran, 2,5-diphenyl-3-ethylfuran, 2,5-di(p-methylphenyl)furan, 2,5-di(2,4-dimethylphenyl)furan, 2,5-di(p-butylphenyl)furan, 2,5-di(p-benzylphenyl)furan, 2-phenyl-5-(p-biphenyl)furan, 2,5-di(p-biphenyl)furan, 2-phenyl-5-( $\alpha$ -naphthyl)furan, 2,5-diphenyloxazole, 2,5-diphenyl-3-methyloxazole, 2,5-di(p-isopropylphenyl)oxazole, 1,4-bis(2-(5-phenyloxazolyl))benzene, 1,4-bis(2-(4-methyl-5-phenyloxazolyl))benzene, 2-phenyl-5-(p-biphenyl)oxazole, 2-phenyl-5-( $\alpha$ -naphthyl)oxazole, 2,5-di( $\alpha$ -naphthyl)oxazole, 1,4-bis(2-(5-phenyloxazolyl))naphthalene, 2,5-di( $\alpha$ -naphthyl)-1,3,4-oxadiazole, 2-phenyl-5-( $\alpha$ -naphthyl)-1,3,4-oxadiazole, 2,5-di(p-t-butylphenyl)-1,3,4-oxadiazole, 2,5-di(4-methyl-1-naphthyl)-1,3,4-oxadiazole, 2-phenyl-5-(p-biphenyl)-1,3,4-oxadiazole, 2-(4-biphenyl)-5-(4-t-butylphenyl)-1,3,4-oxadiazole, and 1,4-bis(2-(5-phenyl-1,3,4-oxadiazolyl))benzene,

wherein the acid value of component (A) is 45-200 mg KOH/g, and

wherein component (A) contains polymerizable monomer with a carboxyl group, (meth)acrylic acid alkyl esters, and styrene or a styrene derivative as a copolymerizing component, component (B) contains a bisphenol A-type (meth)acrylate compound, and component (C) contains a 2,4,5-triarylimidazole dimer.

21. (Cancelled)

22. (Cancelled)

23. (NEW) A photosensitive resin composition according to Claim 1, wherein the component (C) contains 1.0 to 2.0 parts by weight of 2,4,5-triarylimidazole dimer, with respect to 100 parts by weight as the total of component (A) and component (B).

24. (NEW) A photosensitive resin composition according to Claim 1, wherein the component (A) contains 0.1 to 30 wt% of the styrene or styrene derivative as a copolymerizing component, with respect to the total amount of component (A).

25. (NEW) A resist pattern forming method that comprises the steps of:  
laminating a photosensitive resin composition layer for a photosensitive element according to Claim 6 on a circuit forming board;  
irradiating prescribed sections of the photosensitive resin composition layer with active light rays for photocuring of exposed sections; and  
removing non-exposed sections by developing with 0.1 to 5.0 wt% of sodium carbonate dilute solution, or with 0.1 to 5.0 % wt% of potassium carbonate dilute solution, or with 0.1 to 5.0 % wt% of sodium hydroxide dilute solution.

26. (NEW) A process for manufacturing a printed circuit board that comprises the step of:  
etching or plating a circuit forming board having a resist pattern formed thereon by a resist pattern forming method according to claim 25.